

AMENDMENTS TO THE CLAIMS:

This listing of claims replaces all prior versions and listings of claims in the application.

LISTING OF CLAIMS:

1. (Currently Amended) An electronic component comprising:

a multi-layer substrate having an upper side and under side, the multi-layer substrate comprising at least one integrated impedance converter, the at least one integrated impedance converter being configured to perform impedance conversion of at least a factor of two; and

at least one chip component comprising external contacts, the at least one chip component being disposed on the upper side of the multi-layer substrate, the at least one chip component being electrically connected to the at least one integrated impedance converter.
2. (Previously Presented) The electronic component of claim 1, wherein the external contacts comprise surface mounted device contacts.
3. (Previously Presented) The electronic component of claim 1, wherein the multi-layer substrate comprises at least one passive circuit element or at least one active circuit element.
4. (Previously Presented) The electronic component of claim 1, wherein the at least one chip component comprises at least one filter circuit.

5. (Previously Presented) The electronic component of claim 1, wherein the at least one chip component comprises at least one resonator that operates with surface acoustic waves.

6. (Previously Presented) The electronic component of claim 1, wherein the at least one chip component comprises a resonator that operates with bulk acoustic waves.

7. (Previously Presented) The electronic component of claim 1, wherein the at least one chip component comprises a microwave ceramic filter.

8. (Previously Presented) The electronic component of claim 1, wherein the at least one chip component comprises an inductive-capacitive (LC) chip filter.

9. (Previously Presented) The electronic component of claim 1, wherein the at least one chip component comprises a stripline filter.

10. (Previously Presented) The electronic component of claim 1, further comprising:
at least one discrete circuit element disposed on the upper side of the multi-layer substrate, the at least one discrete circuit element comprising an active circuit element or a passive circuit element.

11. (Previously Presented) The electronic component of claim 10, wherein the at least one discrete circuit element comprises at least a part of one of the following: a high-frequency

circuit, an adjustment circuit, an impedance converter, an antenna circuit, a diode circuit, a high-pass filter, a low-pass filter, a band-pass filter, a band elimination filter, a power amplifier, a diplexer, a duplexer, a coupler, a directional coupler, a memory element, a balun, and a mixer.

12. (Previously Presented) The electronic component of claim 10, wherein the at least one discrete circuit element comprises at least a part of a high-frequency circuit, a duplexer or a diplexer; and

wherein the at least one discrete circuit element assists in connecting the at least one chip component to an antenna.

13. (Currently Amended) The electronic component of claim 1, further comprising:
at least one circuit element integrated in the multi-layer substrate[[;]], wherein the at least one circuit element comprises at least a part of one of the following: a high-frequency circuit, an adjustment circuit, an antenna circuit, a diode circuit, a high-pass filter, a low-pass filter, a band-pass filter, a band elimination filter, a power amplifier, a diplexer, a duplexer, a coupler, a directional coupler, a memory element, a balun, and a mixer.

14. (Previously Presented) The electronic component of claim 13, wherein at least a part of an adjustment circuit integrated in the multi-layer substrate is formed as one or more strip conductors on the upper side of the multi-layer substrate.

15. (Previously Presented) The electronic component of claim 1, wherein the multi-layer substrate comprises a plurality of adjustment circuits.

16. (Previously Presented) The electronic component of claim 1, wherein the multi-layer substrate comprises ceramic layers.

17. (Currently Amended) The electronic component of claim 1, wherein the multi-layer substrate comprises layers of ~~silicone or silicone~~ silicon or silicon oxide.

18. (Previously Presented) The electronic component of claim 1, wherein the multi-layer substrate comprises one or more layers of an organic material.

19. (Previously Presented) The electronic component of claim 1, wherein the at least one chip component comprises one or more inputs and outputs; and

wherein at least one input and/or at least one output of the at least one chip component conducts an asymmetrical signal.

20. (Previously Presented) The electronic component of claim 1, wherein the at least one chip component comprises one or more inputs and outputs; and

wherein at least one input and/or the at least one output of the at least one chip component conducts a symmetrical signal.

21. (Previously Presented) The electronic component of claim 1, wherein the at least one chip component comprises a connection to ground, the connection to ground being made via an adjustment circuit that is at least partially integrated in the multi-layer substrate; and wherein the adjustment circuit comprises at least one of a coil, a capacitor and a conductor.

22. (Previously Presented) The electronic component of claim 10, wherein the at least one chip component and the at least one discrete circuit element comprise surface mounted design elements.

23. (Previously Presented) The electronic component of claim 1, wherein the at least one chip component comprises a housing comprising the external contacts.

24. (Currently Amended) The electronic component of claim 1, wherein the at least one chip component (~~CB~~) is connected to the multi-layer substrate via wire bonding.

25. (Previously Presented) The electronic component of claim 1, wherein the at least one chip component is connected to the multi-layer substrate via flip-chip technology.

26. (Previously Presented) A method of producing an electronic component comprised of (i) a multi-layer substrate having an upper side and under side, the multi-layer substrate

comprising at least one integrated impedance converter, and (ii) at least one chip component comprising external contacts, the method comprising:

installing the at least one chip component in a housing; and

mounting the housing onto the upper side of the multi-layer substrate so as to electrically connect the at least one chip component to the integrated impedance converter.

27. (Previously Presented) The method of claim 26, further comprising:

mounting at least one discrete circuit element on the upper side of the multi-layer substrate.

28. (Previously Presented) The method of claim 27, wherein the at least one chip component and the at least one discrete circuit element are attached to the upper side of the multi-layer substrate using a same attaching mechanism.

29. (Previously Presented) The method of claim 27, wherein the at least one chip component and/or the at least one discrete circuit element is mechanically stabilized using a casting compound.